

Harvatek 5.0mm Round LED LAMP HV-52G3304C-L51-TR1-J0004

Official Product	HV-52G3304C-L51-TR1-J0004	Customer Part No.		Data Sheet No.
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- 2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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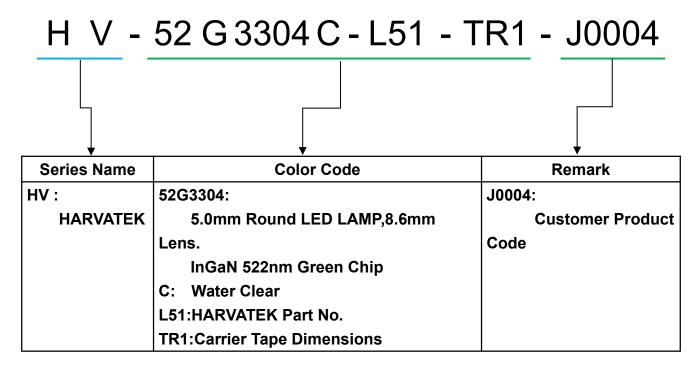


Compliance and Certification

ISO9002, QS9000 and ISO14001 Certified RoHS Compliant



Orderable Information



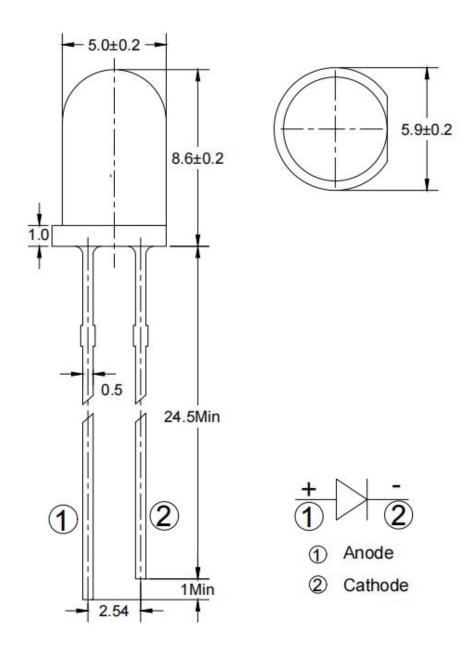
Features:

- Stable Color
- Popular 5.0mm through hole package, 8.6mm lens height.
- Water clear lens

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Package Dimensions:



Notes:

- 1.All dimensions are millimeters.
- 2. Tolerance is +/-0.25mm unless otherwise noted.
- 3. Specifications are subject to change without notice.

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Absolute Maximum Ratings at Ta=25℃

Parameter	Symbol	Rating	Unit
Forward Current	${ m I}_{ m F}$	30	mA
Operating Temperature	$\mathrm{T}_{\mathrm{opr}}$	-40to+85	$^{\circ}$
Storage Temperature	$T_{ m stg}$	-40to+100	$^{\circ}$
Soldering Temperature*1	T_{sol}	260±5	$^{\circ}$
Power Dissipation	P_d	100	mW
Reverse Voltage	V_R	5	V
Peak Forward Current*2	I_{FP}	0.1	A

^{*1:}Soldering time \leq 5 seconds. *2.Pulse Width \leq 100 μ s and Duty \leq 1%.

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Electrical and Optical Characteristic

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Forward Voltage	V_{F}	I _F =20 mA	/	2.8	3.5	V
Reverse Current	I_R	V _R = 5 V	/	/	10	μА
Luminous Intensity	$I_{ m V}$	I _F =20 mA	10000	25000	/	mcd
Viewing Angle	201/2	I _F =20 mA	/	20	/	deg
Dominant Wavelength	λd	I _F =20 mA	518	522	/	nm
Peak Wavelength	λρ	I _F =20 mA	515	520	/	nm
Spectrum Radiation Bandwidth	Δλ	I _F =20 mA	/	30	/	nm

Notes: θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

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Specifications for Bin Grading:

lv (mcd)				
Grade	Min.	Max.		
Z2	10000	18000		
Z3	15000	24000		
Z4	20000	32000		
Z5	25000	40000		

λd (nm)				
Grade	Min.	Max.		
2	518. 5	521. 5		
3	520. 5	523. 5		
4	522. 5	525. 5		
5	524. 5	527. 5		
6	526. 5	529. 5		

Notes:

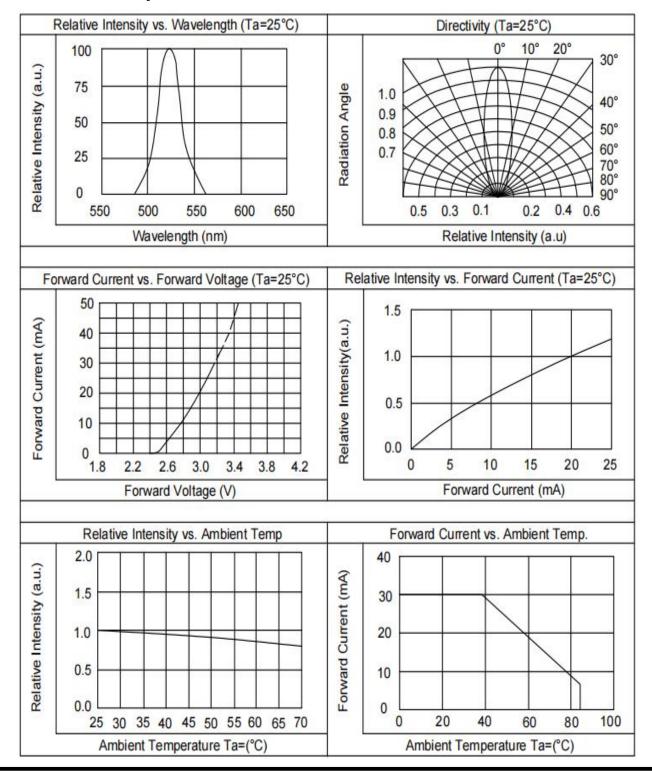
1.Luminous intensity:+/-15%.

2.Wavelength: +/-1nm.

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Typical Electro-Optical Characteristics Curves



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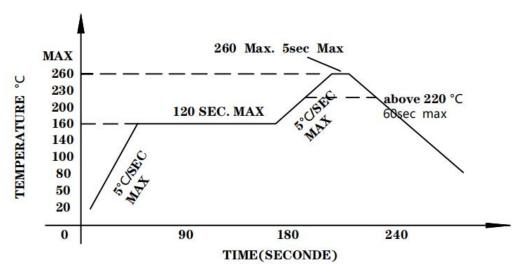


Soldering condition

- 1. Careful attention should be paid during soldering. When soldering, leave more then 2mm from solder joint to Led, and soldering beyond the base of the tie bar is recommended.
- 2. Avoiding applying any stress to the lead frame while the LED are at high temperature particularly when soldering.
- 3. Dip and hand soldering should not be done more than one time.
- 4. After soldering the LED, the epoxy bulb should be protected from mechanical shock or vibration until the LED return to room temperature.
- 5. A rapid-rate process is not recommended for cooling the LED down from the peak temperature.
- 6. Although the recommended soldering conditions are specified in the above table, dip or hand soldering at the lowest possible temperature is desirable for the LED.
- 7. Wave soldering parameter must be set and maintain according to recommended temperature and dwell time in the solder wave.

Recommended soldering conditions

Hand Soldering		Wave Soldering		
Temp. at tip of iron	300°C Max. (30W Max.)	Preheat temp.	160°C Max. (120 sec Max.)	
Soldering time	3 sec Max.	Bath temp. & time	260 Max., 5 sec Max	
Distance	2mm Min.(From solder joint to	Distance	2mm Min. (From solder joint	
Distance	Led)	Distance	to Led)	



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Reliability test items and conditions:

The reliability of products shall be satisfied with items listed below.

Confidence level: 97%

LTPD:3%

No	Item	Test Conditions	Test Hours/Cycle	Sample Size	Failure Judgment Criteria	Ac/Er
1	Solder Heat	TEMP:260°C±5	10 SEC	76 PCS		0/1
2	Temperature Cycle	H:+100°C 15min ∫ 5min L:-40°C 15min	300 CYCLES	76 PCS		0/1
3	Thermal Shock	H:+100°C 5min ∫ 10sec L:-10°C 5min	300 CYCLES	76 PCS	$Iv \leq Ivt*0.5$ or	0/1
4	High Temperature Storage	TEMP:100°C	1000 HRS	76 PCS	Vf≧U or Vf≦L	0/1
5	Low Temperature Storage	TEMP:-40°C	1000 HRS	76 PCS	VI=L	0/1
6	DC Operating Life	TEMP:25°C IF=20mA	1000 HRS	76 PCS		0/1
7	High Temperature / High Humidity	85°C/85%RH	1000 HRS	76 PCS		0/1

Note: Ivt: To test Iv value of the chip before the reliability test.

Iv: The test value of the chip that has completed the reliability test

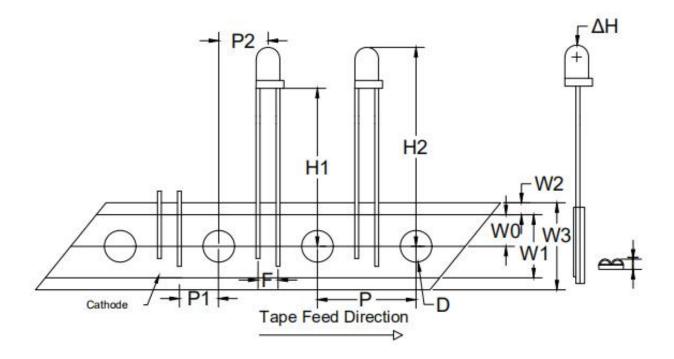
U: Upper Specification Limit

L: Lower Specification Limit

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Carrier Tape Dimensions:



Notes:

Lead spacing is measured where the lead emerge from the package.

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Taping Sizes

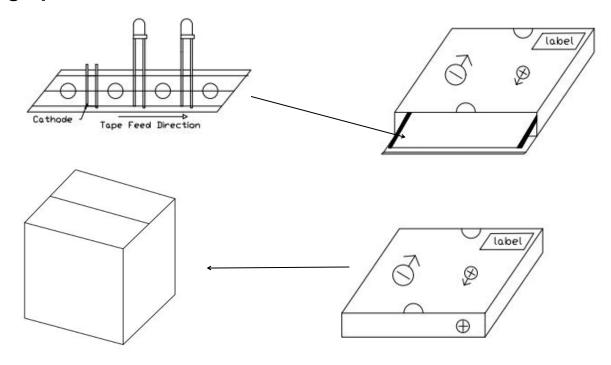
		Specifications			
Symbol Items	Symbol	Av	Avg.		
		mm	Inch	(mm)	
Tape Feed Hole Diameter	D	4	0.157	±0.2	
Component Lead Pitch	F	2.54	0.100	±1.0	
Front-to-Read Deflectio	ΔΗ	2	0.079	±5°	
Feed Hole to Button of Component	H1	20.5	0.807	±1.0	
Feed Hole to Overall Component Height	H2	29.1	1.146	±1.0	
Feed Hole Pitch	P	12.5	0.492	±0.3	
Lead Location	P1	5	0.197	±1.0	
Center of Component Location	P2	6.25	0.246	±1.2	
Overall Taped Package Thickness	T	1.42	0.056	MAX	
Feed Hole Location	W0	6.75	0.266	±0.5	
Adhesive Tape Width	W1	13	0.531	±0.5	
Adhesive Tape Position	W2	2.25	0.089	±1.0	
Tape Width	W3	18	0.709	±1.0	

Note: Tolerances unless mentioned ± 0.1 mm. Unit = mm

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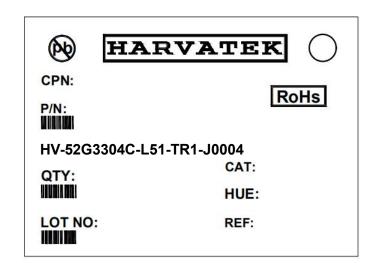


Packing Specification:



Packing Quantity: 2000 PCS/In-Carton, 20000PCS/Out-Carton Note:

After packing into the box, the head is located in the box large negative symbol upward, positive symbol facing themselves



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Revision History

Revision	Page	Version No.	Revision Date
Initial Release		1.0	09-10-2020
Modification of electrical properties	6	1.1	10-20-2020
Modify the wavelength grade code and Replace packaging and increase overfurnace conditions	7/9/11/1 2/13	1.2	09-24-2021
Add the seal stamped position	14	1.3	09-28-2021

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